# SN54LS682, SN54LS684, SN54LS685, SN54LS687, SN54LS688, SN74LS682, SN74LS684 THRU SN74LS688 8-BIT MAGNITUDE/IDENTITY COMPARATORS

SDLS008

D2617, JANUARY 1981 - REVISED MARCH 1988

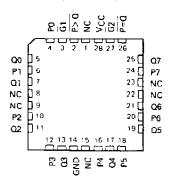
- Compares Two-8-Bit Words
- Choice of Totem-Pole or Open-Collector Outputs
- Hysteresis at P and Q Inputs
- 'LS682 has 20-kΩ Pullup Resistors on the Q Inputs
- SN74LS686 and 'LS687 . . . JT and NT 24-Pin, 300-Mil Packages

TYPE	P = Q	P > 0	OUTPUT	QUTPUT	20-kΩ
	r = u	F > U	ENABLE	CONFIGURATION	PULLUP
'LS682	yes	yes	no	totem-pole	yes
'L5684	yes	yes	no	totem-pole	no
'LS685	<b>∀9</b> 5	γes	na	open-collector	no
SN74LS686	yes	ves	yes	totem-pole	no
'LS687	yes	yes	yes	open-collector	no
'L5688	yes	no	yes	totem-pole	no

SN54LS687 . . . JT PACKAGE SN74LS686, SN74LS687 . . . DW OR NT PACKAGE (TOP VIEW)

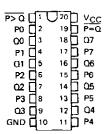
P> 0 C G1 C P0 C P1 C O1 C NC C P2 C P3 C O3 F	1 2 3 4 5 6 7 8 9	24 23 22 21 20 19 18 17 16 15 14	VCC G2 P=0 Q7 P7 NC Q6 P6 Q5 P5 Q4
	1	Ė	_

\$N54L\$687 . . . FK PACKAGE (TOP VIEW)

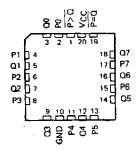


NC-No internal connection

\$N54L\$682, \$N54L\$684, \$N54L\$685 . . . J PACKAGE \$N74L\$682, \$N74L\$684, \$N74L\$685 . . . DW OR N PACKAGE (TOP VIEW)

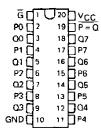


SN54LS682, SN54LS684, SN54LS685 . . . FK PACKAGE (TOP VIEW)



SN54LS688 . . . J PACKAGE SN74LS688 . . . DW OR N PACKAGE

(TOP VIEW)



SN54LS688 . . . FK PACKAGE (TOP VIEW)

## SN54LS682, SN54LS684, SN54LS685, SN54LS687, SN54LS688 SN74LS682, SN74LS684 THRU SN74LS688 8-BIT MAGNITUDE/IDENTITY COMPARATORS

#### description

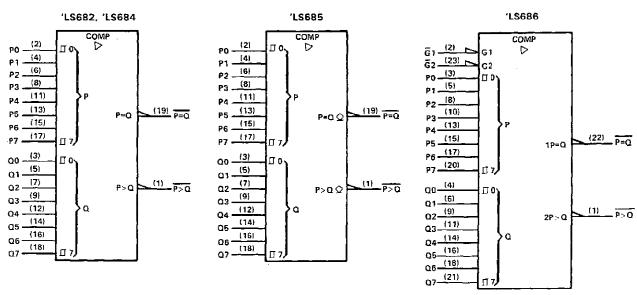
These magnitude comparators perform comparisons of two eight-bit binary or BCD words. All types provide  $\overline{P}=\overline{Q}$  outputs and all except 'LS688 provide  $\overline{P}>\overline{Q}$  outputs as well. The 'LS682, 'LS684, 'LS685, and 'LS688 have totem-pole outputs, while the 'LS685 and 'LS687 have open-collector outputs. The 'LS682 features 20-k $\Omega$  pullup termination resistors on the Q inputs for analog or switch data.

#### **FUNCTION TABLE**

	INPUTS		OUTI	PUTS
DATA	ENAB	ES	<b>P=0</b>	P>Q
P, Q	Ğ, <u>G1</u>	G2		.,,
P=Q	L	Х	L	н
P>Q	×	Ļ	н	L
P <q< td=""><td>X</td><td>X</td><td>н</td><td>Н_</td></q<>	X	X	н	Н_
P = Q	Н	X	Н	Н
P>Q	×	Н	] н	Н
×	Н	] н	Н	н

- NOTES: 1. The last three lines of the function table applies only to the devices having enable inputs, i.e., 'LS686 thru 'LS688.
  - 2. The  $\overline{P < Q}$  function can be generated by applying the  $\overline{P Q}$  and  $\overline{P > Q}$  outputs to a 2-input NAND gate.
  - 3. For 'LS686 and 'LS687,  $\overline{G}$ 1 enables  $\overline{P} = \overline{Q}$  and  $\overline{G}$ 2 enables  $\overline{P} > \overline{Q}$ .

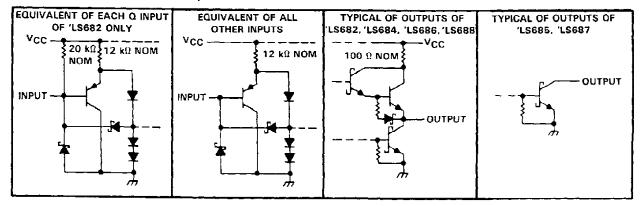
### logic symbols†



 $^{\dagger}$ These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, J, JT, N, and NT packages.

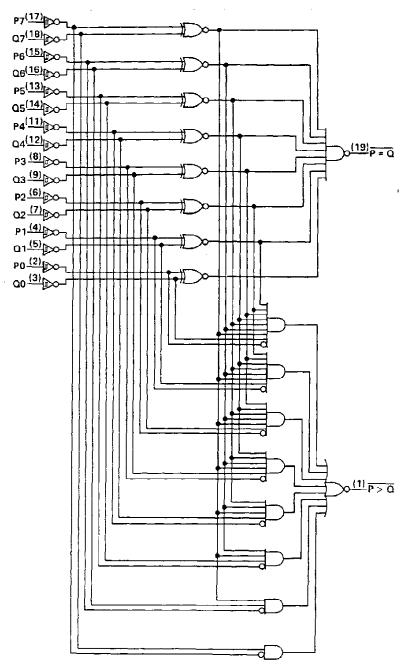
#### logic symbols† (continued) 'LS687 'LS688 COMP COMP 12) ãi. P0 (2) G1 Ğ2 (23) ► G2 ە □ (3) P1 (4) PO. ים דו (5) (6) P2 -(8) P3 (B) P2 -P4 (11) (10) P3 (13) (13) P5 -1151 (22) P=0 (15) P5 -1₽=0 ☆ P6 -P6 [17] P7 (17) (19) P=Q رد 🛚 P7 (20) 1P=Q ք 7 00 (3) [] Or (4) 01 (5) Q0-Πο, Q1 (6) Q2 (7) Q2 (9) Q3 (9) (1) 03 (11) 2P -Q Q 04 (12) ò (14) Q Q5 (16) Q4-Q5 (16) Q6• 06 (18) 07 (18) 07- (21)

### schematics of inputs and outputs



<sup>&</sup>lt;sup>†</sup>These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, J, JT, N, and NT packages.

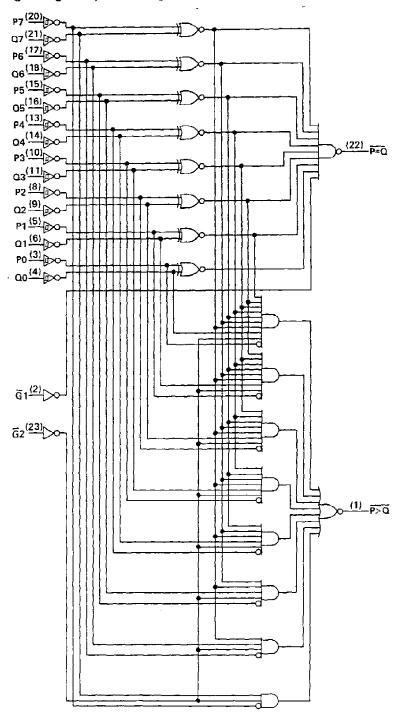
'LS682, 'LS684, 'LS685 logic diagram (positive logic)



Pin numbers shown are for DW, J, and N packages.



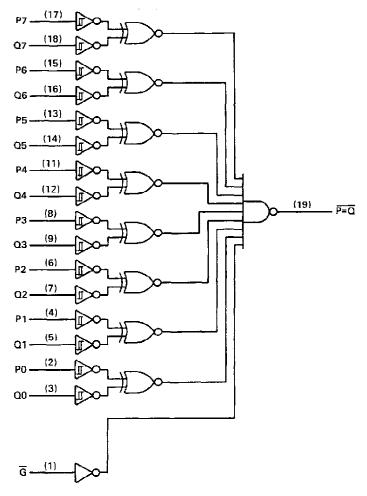
### 'LS686, 'LS687 logic diagram (positive logic)



Pin numbers shown are for DW, JT, and NT packages.



### 'LS688 logic diagram (positive logic)



Pin numbers shown are for DW, J, and N packages.

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage: Q inputs of 'LS682	, <b>5</b> .5 V
All other inputs	
Off-state output voltage: 'LS685, 'LS687	
Operating free-air temperature range:	
SN54LS682, SN54LS684, SN54LS685, SN54LS687, SN54LS688	-55°C to 125°C
SN74LS682, SN74LS684 thru SN74LS688	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



# SN54LS682, SN54LS684, SN54LS688 SN74LS682, SN74LS684, SN74LS686, SN74LS688 8-BIT MAGNITUDE/IDENTITY COMPARATORS WITH TOTEM-POLE OUTPUTS

### recommended operating conditions

		SN54LS'			SN74LS'		
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, VCC	4.5	5	5.5	4.85	5	5.25	>
High-level output current, IOH			-400			-400	μΑ
Low-level output current, IOI			12			24	mΑ
Operating free-air temperature, TA	- 55		125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		_				SN54LS	3'	S	N74LS	•	UNIT
	PARAMETE	R	TEST CO	VDITIONS <sup>†</sup>	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNII
V <sub>IH</sub>	High-level inpu	ut voltage			2			2			V
VIL	Low-level inpu	ut voltage					0.7			0.8	V
	. Hysteresis	P or Q inputs	V <sub>CC</sub> = MIN			0.4			0.4		٧
VIK	Input clamp v	oltage	VCC = MIN.	ij = -18 mA			-1.5			- 1.5	>
Voн	High-level out	put voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = V <sub>IL</sub> max,	$V_{1H} = 2 V$ , $I_{OH} = -400 \mu A$	2.5			2.7			>
VOL	Low-level out	out voltage	$V_{CC} = MIN,$ $V_{IH} = 2 V,$	IOL = 12 mA		0.25	0.4		0.25	0.4	٧
		pat voltage	V <sub>IL</sub> = V <sub>IL</sub> max	iOL = 24 mA					0.35	0.5	
h	Input current at maximum	Q inputs, 'LS682	VCC = MAX,	V <sub>1</sub> = 5.5 V			0.1			0.1	mA
'I 		All other inputs	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 7 V			0.1				,,,,,
ΊΗ	High-level inp	ut current	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 2.7 V			20			20	μA
կլ		Q inputs, 'LS682' All other inputs	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 0.4 V			-0.4 -0.2			-0.4 -0.2	mA
los§	Short-circuit o	output current	VCC = MAX.	Vo = 0	- 20		- 100	- 20		- 100	mA
		'LS682				42	70		42	70	
loc.	Supply curren	'LS684	Voc - MAY	See Note 1		40	65		40	65	mA
CC	Supply cutten	'LS686	V <sub>CC</sub> = MAX,	SEE MOTE 1		44	75		44	75	
		'LS688				40	65		40	65	

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions.

 $<sup>^{\</sup>ddagger}$  All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25 °C.

Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 1: ICC is measured with any G inputs grounded, all other inputs at 4.5 V, and all outputs open.

# SN54LS682, SN54LS684, SN54LS688 SN74LS682, SN74LS684, SN74LS686, SN74LS688 8-BIT MAGNITUDE/IDENTITY COMPARATORS WITH TOTEM-POLE OUTPUTS

# switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER†	FROM	TO	TEST	'LS68	2	'LS68	4	'LS68	6	'LS68	8	UNIT
LANAMETER.	(INPUTS)	(OUTPUT)	CONDITIONS	MIN TYP	MAX	MIN TYP	MAX	MIN TYP	MAX	MIN TYP	MAX	UNIT
t <sub>PLH</sub>	P	P≖Q	•	13	25	15	25	13	25	12	18	
t <sub>PHL</sub>		1		15	25	17	25	20	30	17	23	ns
<sup>t</sup> PLH	α	$\overline{P} = \overline{Q}$		14	25	16	25	13	25	12	18	
tPHL_	<u> </u>	r = Q	R <sub>I</sub> = 667 Ω,	15	25	15	25	21	30	17	23	ns
tPLH.	G, G1	P=O	· ·					11	20	12	18	ns
<sup>t</sup> PHL	G, G1		CL = 45 pF,					19	30	13	20	i ns
tPLH	Р	P>Q	All other	20	30	22	30	19	30			
tPHL	<u>-</u>	r>u	inputs low, See Note 2	15	30	17	30	15	30			ns
†PLH	0	P>0	See Note 2	21	30	24	30	18	30		•	
tPHL	u	טכה		19	30	20	30	19	30			ns
<sup>t</sup> PLH	Ğ2	₽>Q				<u>-</u>		21	30			
tpHI	<u> </u>	P>U						16	25			ns

 $<sup>^{\</sup>dagger}$ tpLH = propagation delay time, low-to-high-level outputs; tpHL = propagation delay time, high-to-low-level output. NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

# SN54LS685, SN54LS687 SN74LS685, SN74LS687, SN74LS688 8-BIT MAGNITUDE/IDENTITY COMPARATORS WITH TOTEM-POLE OUTPUTS

### recommended operating conditions

		SN54L8	3'	S	N74LS		UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, VCC	4.5	5	5.5	4.85	5	5.25	V
High-level output current, VOH			5.5			5.5	V
Low-level output current, IQL			12			24	mA
Operating free-air temperature, TA	- 55		125	0		70	°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DARAMETER		uziono!	5	N54L	3'	s	N74LS	•	UNIT
	PARAMETER	TEST CONE	MIN	TYP	MAX	MIN	TYP	MAX	ONIT	
ViH	High-level input voltage			2			2			٧
VIL	Low-level input voltage					0.7			8.0	V
V <sub>T+</sub> - '	V <sub>T</sub> _ Hysteresis P or Q inputs	VCC = MIN			0.4			0.4		٧
$V_{IK}$	Input clamp voltage	VCC = MIN,	I <sub>I</sub> = -18 mA			- 1.5			-1.5	٧
Іон	High-level output voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = V <sub>IL</sub> max,	V <sub>IH</sub> = 2 V, V <sub>OH</sub> = 5.5 V			250			100	μА
Vol	Low-level output voltage	$V_{CC} = MIN,$ $V_{IH} = 2 V,$	I <sub>OL</sub> = 12 mA		0.25	0.4		0.25	0.4	v
- OL	as in love surput valuage	VIL = VILmax	l <sub>OL</sub> = 24 mA					0.35	0.5	1
Iq		VCC = MAX,	V <sub>1</sub> = 7 V			0.1			0.1	mA
_'IH	High-level input current	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 2.7 V			20			20	μΑ
IIL	Low-level input current	V <sub>CC</sub> ≈ MAX,	V <sub>1</sub> = 0.4 V			-0.2			-0.2	mA
	Supply 'LS685		Con Nove 1		40	65		40	65	A
lcc	current 'LS687	$V_{CC} = MAX,$	See Note 1		44	75		44	75	mA

 $<sup>^{\</sup>dagger}$  For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions.

 $<sup>^{\</sup>ddagger}$ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25 °C. NOTE 1: I<sub>CC</sub> is measure with any  $\overline{G}$  inputs grounded, all other inputs at 4.5 V, and all outputs open.

# SN54LS685, SN54LS687 SN74LS685, SN74LS687 8-BIT MAGNITUDE/IDENTITY COMPARATORS WITH OPEN-COLLECTOR OUTPUTS

# switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER	FROM	то	7507 00101710110		'LS685			'LS687		UNIT			
PARAIVIETER	(INPUT)	(OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	ONT			
tPLH	P	P=Q			30	45		24	35				
†PHL	F	P=U	ļ r=u	) r=u	)			19	35		20	30	ns
tPLH.	Q	P≂Œ			24	45		24	35				
<sup>t</sup> PHL	<u>u</u>	) P=u }	8. 663.6		23	35		20	30	ns			
tPLH	ਰ, <b>ਰ</b> 1	P=Q	$R_{L} \simeq 667 \Omega$					21	35				
<b>TPHL</b>	G, G1	]	Cլ = 45 pF,					18	30	ns			
t <sub>PLH</sub>	Р	P>Q	All other		32	45		24	35				
<sup>†</sup> PHL	P	P>u	inputs low,		16	35		16	30	ns			
t <sub>PLH</sub>	a	P>Q	See Note 2		30	45		24	35				
tPHL	u	) r>u			20	35		16	30	ns			
tPLH	<u>G</u> 2	B C						24	35				
<sup>†</sup> PHL	G2	P>0						15	30	ns			

 $<sup>^{\</sup>dagger}$ tpLH = propagation delay time, low-to-high-level outputs; tpHL = propagation delay time, high-to-low-level output. NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

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### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
84151012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
8415101RA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
8415101RA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
8415101SA	ACTIVE	CFP	W	20	1	TBD	Call TI	Level-NC-NC-NC
8415101SA	ACTIVE	CFP	W	20	1	TBD	Call TI	Level-NC-NC-NC
84152012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
8415201RA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
8415201SA	ACTIVE	CFP	W	20	1	TBD	Call TI	Level-NC-NC-NC
84153012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
8415301RA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
8415301SA	ACTIVE	CFP	W	20	1	TBD	Call TI	Level-NC-NC-NC
SN54LS682J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SN54LS682J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SN54LS684J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SN54LS688J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SN74LS682DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS682N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS682NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS682NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS682NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS682NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM





26-Sep-2005

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp (3)
SN74LS684DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS684NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS684NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS686DW	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI
SN74LS686NT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI
SN74LS687NT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI
SN74LS687NT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI
SN74LS688DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS688DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS688DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS688DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS688N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS688N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74LS688NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS688NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS688NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54LS682FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS682FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS682J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS682J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS682W	ACTIVE	CFP	W	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS682W	ACTIVE	CFP	W	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS684FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS684J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS684W	ACTIVE	CFP	W	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS688FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS688J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS688W	ACTIVE	CFP	W	20	1	TBD	Call TI	Level-NC-NC-NC



### PACKAGE OPTION ADDENDUM

26-Sep-2005

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# W (R-GDFP-F20)

# CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



### FK (S-CQCC-N\*\*)

#### **28 TERMINAL SHOWN**

### **LEADLESS CERAMIC CHIP CARRIER**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



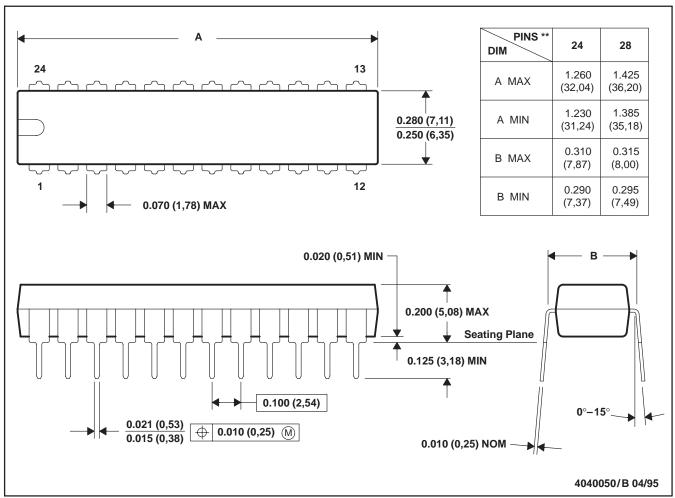
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



### NT (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

### **24 PINS SHOWN**



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

# DW (R-PDSO-G20)

# PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



# DW (R-PDSO-G24)

# PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



### **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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